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TFT | CHARACTER | UWVD | FSC | SEGMENT | CUSTOM | REPLACEMENT

TFT LCD Module

Part Number E20RA-FW700-N

Overview:

- 2.0-inch TFT (46.50x41.56mm)
- 8/9/16/18-bit MCU Interface
- 3/4-wire Serial Interface
- 3/4SPI+16/18 RGB Interface
- White LED back-light

- Transmissive/Normally Black
- No Touch Panel
- 700 NITS
- Controller: ILI9342
- RoHS Compliant



Description

This is a color active matrix TFT (Thin Film Transistor) LCD (Liquid Crystal Display) that uses amorphous silicon TFT as a switching device. This model is composed of a transmissive type TFT-LCD Panel, driver circuit, and a backlight unit. The resolution of the 2.0" TFT-LCD contains 320(RGB)x240 pixels and can display up to 262k colors.

TFT Features

Low Input Voltage: 3.3V

Display Colors: 65k/262k colors

Interface: 3/4-wire serial

8/9/16/18-bit MCU

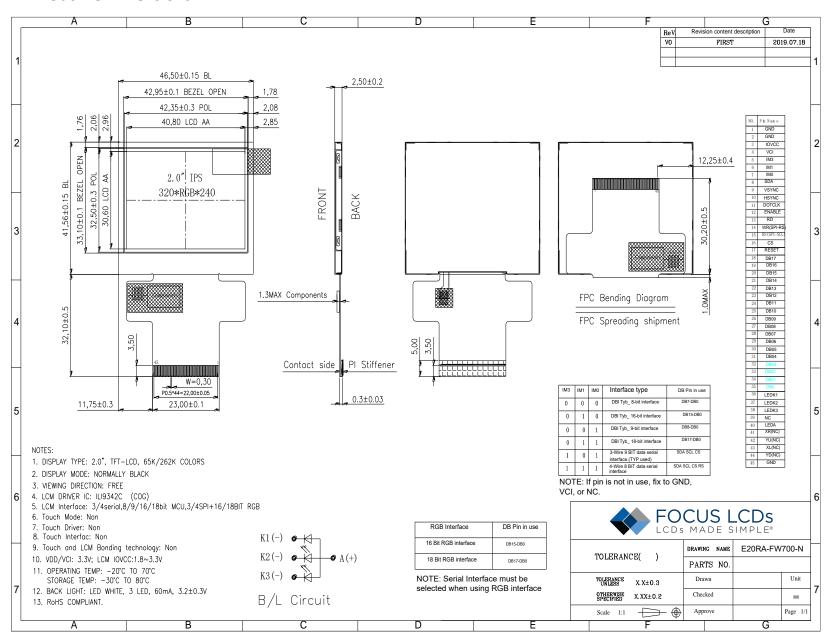
3/4-wire SPI+16/18-bit RGB

General Information Items	Specification Main Panel	Unit	Note
TFT Display area (AA)	40.80(H) x 30.60(V) (2.0 inch)	mm	-
Driver Element	TFT active matrix	-	-
Display Colors	65k/262k	colors	-
Number of pixels	320(RGB)x240	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel Pitch	0.1275x0.1275	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	IL19342C	-	-
Interface	3/4-serial 8/9/16/18-bit MCU 3/4-SPI+16/18-bit RGB	-	-
Display mode	Transmissive/ Normally Black	-	-
Operating temperature	-20∼+70	°C	-
Storage temperature	-30∼+80	°C	-

Mechanical Information

Item		Min	Тур.	Max	Unit	Note
	Horizontal (H)		46.50		mm	-
Module	Vertical (V)		41.56		mm	-
Size	Depth (D)		2.50		mm	-
	Weight		10		g	_

1. Outline Dimensions

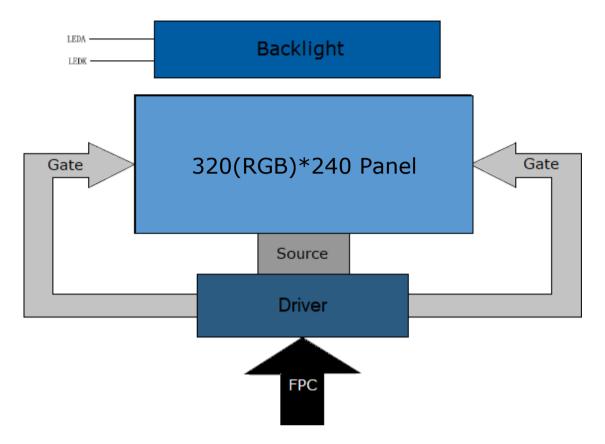


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2. Block Diagram





Input Terminal Pin Assignment Recommended Connector: FH12S-45S-0.5SH(55) 3.

NO. Symbol Description 9						<u> </u>				
Company Comp	NO.	Symbol	Description						1/0	
3	1		Ground	Ground						
VCI	2	GND	Ground						Р	
IM3 Interface In	3	IOVCC	Supply voltag	e (1.8	-3.3V)			Р	
IM3	4	VCI	Supply voltag	e (3.3	V)				Р	
IM3				IM3	IM1	IM0		Pins Used		
Selection				0	0	0	DBI Type 8-bit	DB7-DB0		
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	43	XL(NC)	Not connecte							
45 GND Ground P	44	YD(NC)	Not connecte							
	45	GND	Ground						Р	

I: Input, O: Output, P: Power



4. LCD Optical Characteristics

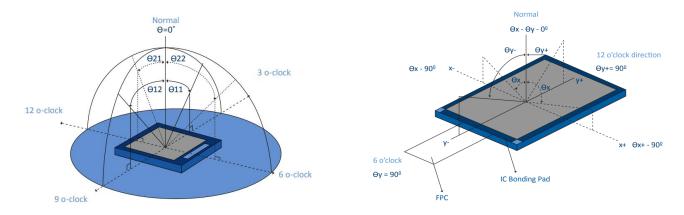
4.1 Optical Specifications

Item		Symbol	Condition	Min	Тур.	Max	Unit	Note
Color Gan	Color Gamut			55	60		%	(3)
Contrast R	atio	CR		1000	1500		%	(2)
Response Time	Rising	TR+TF			30	40	ms	(4)
Response fille	Falling	INTIF			30	40	1113	(4)
	\ \ / - ! + -	W _X	θ=0	0.2599	0.299	0.3399		
	White	W _Y	Normal viewing	0.2858	0.3258	0.3658		
	Red	R _X	angle	0.5889	0.6089	0.6289		
Color Filter		R _Y		0.3441	0.3641	0.3841		(5)(6)
Chromaticity	Croon	G _X		0.3068	0.3268	0.3468		(5)(6)
	Green	G _Y		0.5607	0.5807	0.6007		
	Dlug	B _X		0.1308	0.1508	0.1708		
	Blue	B _Y		0.0640	0.0840	0.1040		
		ΘL		70	80			
Viousing Angle	Hor.	ΘR	CR≥10	70	80		dograa	(1)(6)
Viewing Angle		ΘТ		70	80		degree	(1)(6)
Ver.		ΘВ		70	80			
Option View Di	Option View Direction ALL					(1)		



Optical Specification Reference Notes:

(1) Definition of Viewing Angle: The viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3,9 o'clock direction and the vertical or 6,12 o'clock direction with respect to the optical axis which is normal to the LCD surface.

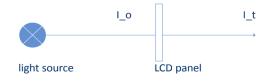


(2) Definition of Contrast Ratio (Cr): measured at the center point of panel. The contrast ratio (Cr) measured on a module, is the ratio between the luminance (Lw) in a full white area (R=G=B=1) and the luminance (Ld) in a dark area (R=G=B=0).

$$Cr = \frac{Lw}{Ld}$$

(3) Definition of transmittance (T%): The transmittance of the panel including the polarizers is measured with electrical driving. The equation for transmittance Tr is:

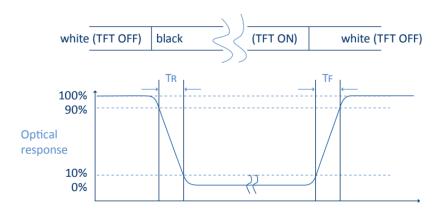
$$Tr = \frac{It}{Io} \times 100\%$$



Io = the brightness of the light source.

It = the brightness after panel transmission

(4) Definition of Response Time (Tr, Tf): The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.





(5) Definition of Color Gamut:

Measuring machine CFT-01. NTSC's Primaries: R(x,y,Y),G(x,y,Y), B(x,y,Y). FPM520 of Westar Display Technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics. The color chromaticity shall be calculated from the spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the panel.

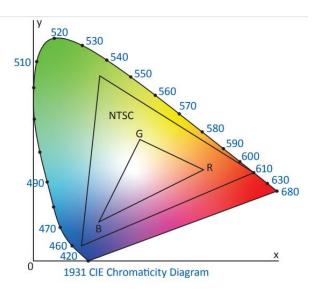
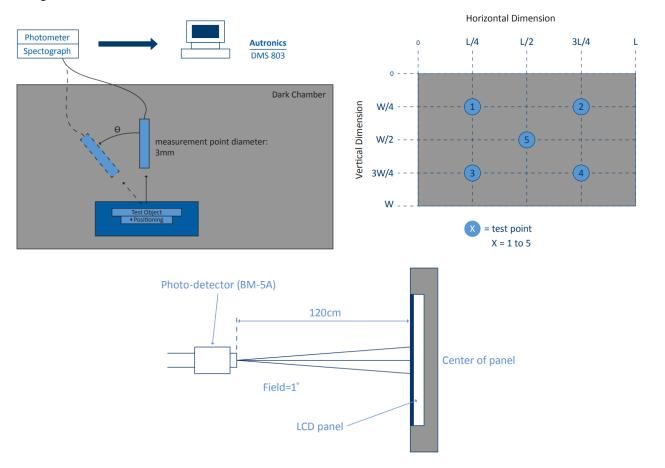


Fig. 1931 CIE chromacity diagram

Color gamut: $S = \frac{\text{Area of RGB triangle}}{\text{Area of NTSC triangle}} \times 100\%$

(6) Definition of Optical Measurement Setup:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 20 minutes.





5. TFT Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 °C, VSS=0V)

Characteristics	Symbol	Min	Max	Unit
Digital Supply Voltage	VDD	-0.3	4.2	V
Digital Interface Supply Voltage	IOVCC	-0.3	3.3	V
Operating Temperature	ТОР	-20	+70	°C
Storage Temperature	TST	-30	+80	°C

NOTE: If the absolute maximum rating of the above parameters is exceeded, even momentarily, the quality of the product may be degraded. Absolute maximum ratings specify the values which the product may be physically damaged if exceeded. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min	Тур.	Max	Unit	Note
Digital Supply Voltage	VCI	2.5	3.3	3.6	V	
Digital Interface Supply Voltage	IOVCC	1.65	1.8	3.3	V	
Normal Mode Current Consumption	IDD		5		mA	
Level Input Voltage	VIH	0.7IOVCC		IOVCC+0.3	V	
Level input voltage	VIL	GND-0.3		0.3IOVCC	V	
Level Output Voltage	VOH	IOVCC-0.4			V	
Level output voltage	VOL	GND		GND+0.4	V	



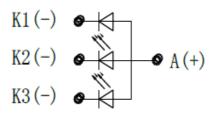
5.3 LED Backlight Characteristics

The backlight system is edge lighting type with 3 chips LED.

Item	Symbol	Min	Тур.	Max	Unit	Note
Forward Current	lF		60		mA	
Forward Voltage	V _F		3.		V	
LCM Luminance	LV		700		cd/m2	Note 3
LED lifetime	Hr		50000		hour	Note1 & 2
Uniformity	AVg	80		1	%	Note 3

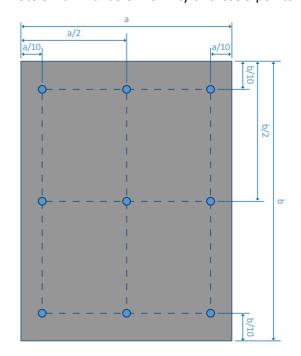
Note 1: LED lifetime (Hr) can be defined as the time in which it continues to operate under the condition: $Ta=25 \pm 3$ °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED lifetime" is defined as the module brightness decrease to 50% original brightness at $Ta=25^{\circ}C$ and IL=60mA



Backlight LED Circuit

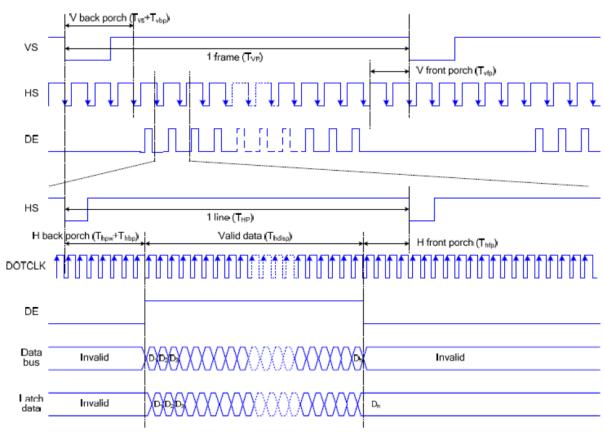
Note 3: Luminance Uniformity of these 9 points is defined as below:





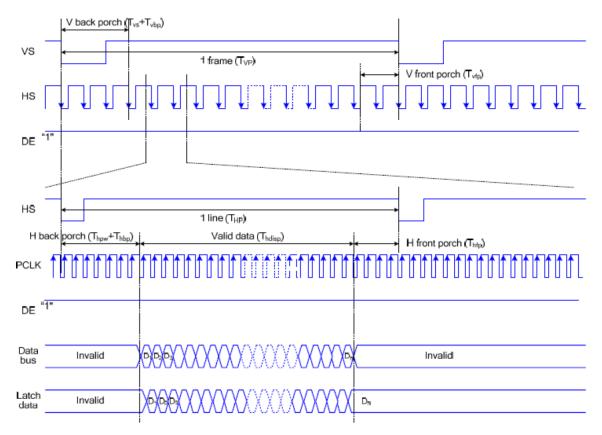
6. RGB Interface Timing Diagram





Note: The setting of front porch and back porch in host must match that in IC as this mode.

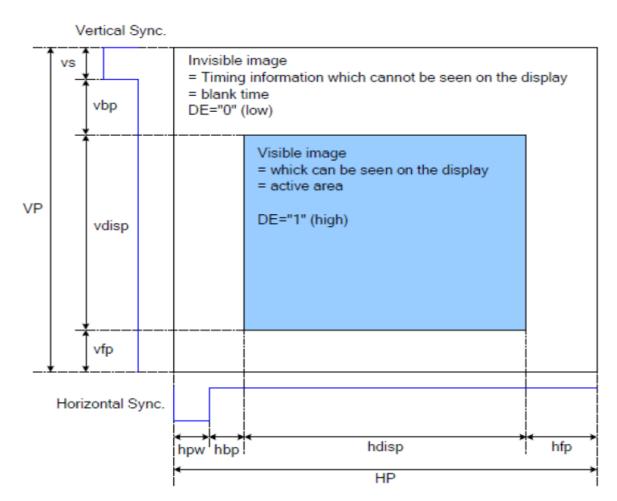
HV Mode





7.5 RGB Interface Definition

The display operation via the RGB interface is synchronized with the VSYNC, HSYNC and DOTCLK signals. The data can be written only within the specified area with low power consumption by using the window address function. The back porch and front porch are used to set the RGB interface timing signals.



Parameter	Symbol	Condition	Min	Тур	Max	Unit
Refresh Rate	fclk			60		Hz
Horizontal sync width	hpw		6		78	Clock
Horizontal back porch	hbp		5		78	Clock
Horizontal front porch	hfp		5		78	Clock
Vertical sync width	VS		2			Line
Vertical back porch	vbp		2			Line
Vertical front porch	vfp		2			Line



6.3 Reset Timing

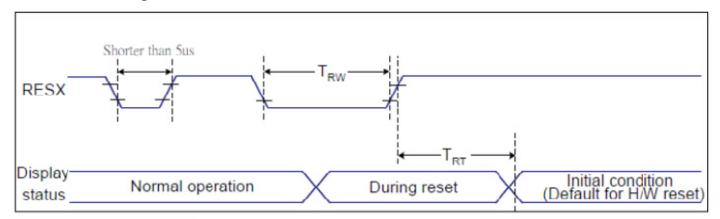


Figure 6.3: Reset Timing Diagram

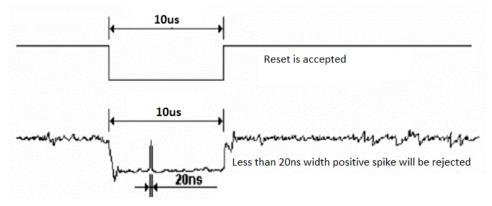
Related Pins	Symbol	Parameter	Min	Max	Unit
	TRW	Reset pulse duration	10	-	us
RESX	TDT	Donat consol	-	5 (Note 1,5)	ms
	TRT	Reset cancel		120 (Note 1, 6, 7)	ms

Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5ms after a rising edge of RESX.
- 2. Spike due to an electrostatic discharge on RESX line does not because irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9 us	Reset starts

- 3. During the resetting period, the display will be blanked (the display is entering blanking sequence, which maximum time is 120ms, when reset starts in Sleep Out mode. The display remains the blank state in Sleep in mode) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- 7. It is necessary to wait 5ms after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120ms.



7. Cautions and Handling Precautions

7.1 Handling and Operating the Module

- 1. When the module is assembled, it should be attached to the system firmly. Do not warp or twist the module during assembly work.
- 2. Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- 3. Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- 4. Do not allow drops of water or chemicals to remain on the display surface. If you have the droplets for a long time, staining and discoloration may occur.
- 5. If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- 6. The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane. Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- 7. If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- 8. Protect the module from static; it may cause damage to the CMOSICs.
- 9. Use fingerstalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- 10. Do not disassemble the module.
- 11. Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- 12. Pins of I/F connector shall not be touched directly with bare hands.
- 13. Do not connect, disconnect the module in the "Power ON" condition.
- 14. Power supply should always be turned on/off by the item Power On Sequence & Power Off Sequence.

7.2 Storage and Transportation

- 1. Do not leave the panel in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- 2. Do not store the TFT-LCD module in direct sunlight.
- 3. The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- 4. It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module. In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- 5. This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.